

REMARKS

Claims 1-10 are pending and under consideration.

In the Office Action of August 20, 2004, claims 1-10 were rejected as obvious over *Uemura, et al.* (USP 2002/0043331A) in view of allegedly admitted prior art. This rejection is traversed.

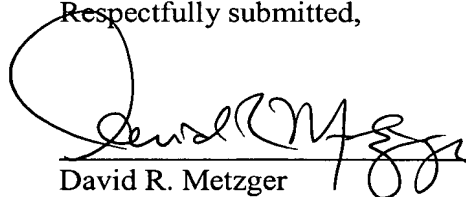
Claims 1, 2 and 7 have been amended to clarify the invention. In particular, independent claim 1 sets forth how an assembly with a laser chip mounted on a base is provided, and then the base and laser chip are subjected to an energy beam to remove adherent from the laser chip and the base. Claims 2 and 7 have been amended to follow claim 1 and to correct idiomatic errors.

In the rejection, the examiner points to *Uemura, et al.* as disclosing irradiation with an energy beam. However, *Uemura, et al.* does not fairly disclose or teach assembling a laser chip on a base and then subjecting both to irradiation effective to remove the adherent. It is the step that ensures that during operation of the semiconductor laser material is not caused to be deposited on the laser beam emitting edge. See paragraphs 0042, 0043 and 0047 of the present specification. This is not a problem or solution recognized in *Uemura, et al.*

It is submitted that the allegedly admitted prior art does not provide the missing disclosure or suggestion. At best, the combination proposed by the examiner would result in the mounting of previously irradiated chips on a base. There is no suggestion to also irradiate the base, much less chips and base together as claimed.

It is submitted that claims 1-10 are patentable and that the application is in condition for allowance. Notice to that effect is requested.

Respectfully submitted,



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